



Product data sheet

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SOD-123FL

FEATURES

- * Ideal for surface mount applications
- * Easy pick and place
- * Built-in strain relief
- * Low forward voltage drop

MECHANICAL DATA

- * Case: Molded plastic
- * Epoxy: UL 94V-0 rate flame retardant
- * Metallurgically bonded construction
- * Polarity: Color band denotes cathode end
- * Mounting position: Any

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Rating 25°C ambient temperature uniess otherwies specified. Single phase half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

	P/N	DS22W -MS	DS23W -MS	DS24W -MS		DS26W -MS		DS29W -MS	DS210W -MS	
	MARK	K22	K23	K24	K25	K26	K28	K29	K210	UNITS
Maximum Recurrent Peak Reverse Voltage	Vrrm	20	30	40	50	60	80	90	100	V
Maximum RMS Voltage	Vrms	14	21	28	35	42	56	63	70	V
Maximum DC Blocking Voltage	VDC	20	30	40	50	60	80	90	100	V
Maximum Average Forward Rectified Current	Lun									
See Fig. 1	l(AV)		2.0							
Peak Forward Surge Current, 8.3 ms single half sine-way	е									
superimposed on rated load (JEDEC method)		40								А
Maximum Instantaneous Forward Voltage at 2.0A	Vf		0.55		0.	70		0.85		V
Maximum DC Reverse Current Ta=25°C		0.1			0.02			mA		
at Rated DC Blocking Voltage Ta=100℃	IR	5 2			mA					
Typical Junction Capacitance (Note1)	Сл	170				pF				
Operating Temperature Range TJ	ΓJ	-65-+150			°C					
Storage Temperature Range Tstg	Тѕтс	-65-+150				°C				
Notes										

NOTES:

1. Measured at 1MHz and applied reverse voltage of 4.0V D.C.

2. Thermal Resistance Junction to Ambient.

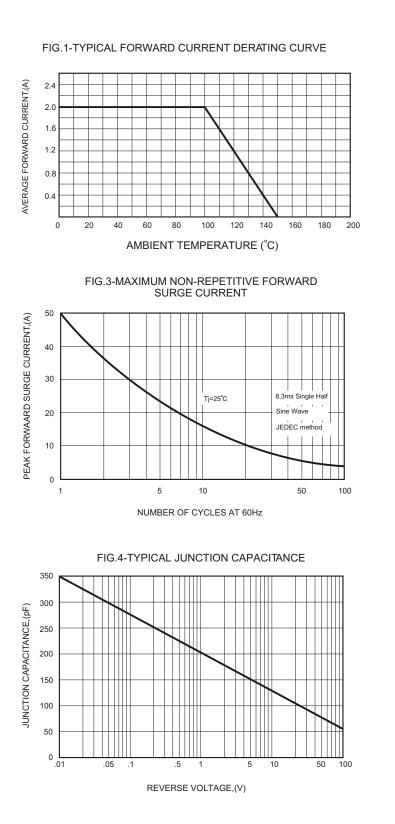




DS22W-MS THRU DS210W-MS

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RATING AND CHARACTERISTIC CURVES (K22 THRU K210)

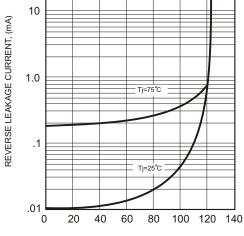


CHARACTERISTICS 50 INSTANTANEOUS FORWARD CURRENT,(A) 10 3.0 1.0 Tj=25℃ ulse Width 300u 1% Duty Cycle 0.1 .01 .3 1.3 1.5 .1 .5 .7 .9 1.1 FORWARD VOLTAGE,(V)

FIG.2-TYPICAL FORWARD

100 CHARACTERISTICS

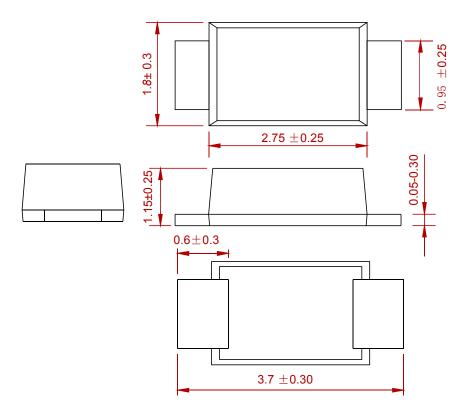
FIG.5 - TYPICAL REVERSE





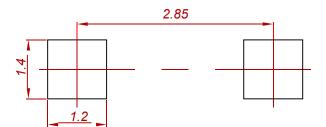
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PACKAGE MECHANICAL DATA



Dimensions in millimeters

Suggested Pad Layout



Note:

1.Controlling dimension:in millimeters.

- 2.General tolerance:±0.05mm.
- 3. The pad layout is for reference purposes only.

REEL SPECIFICATION

P/N	PKG	QTY
DS22W-MS THRU DS210W-MS	SOD-123FL	3000



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